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(54) Title: CHEMICAL-MECHANICAL POLISHING COMPOSITION COMPRISING ORGANIC/INORGANIC COMPOSITE PARTICLES

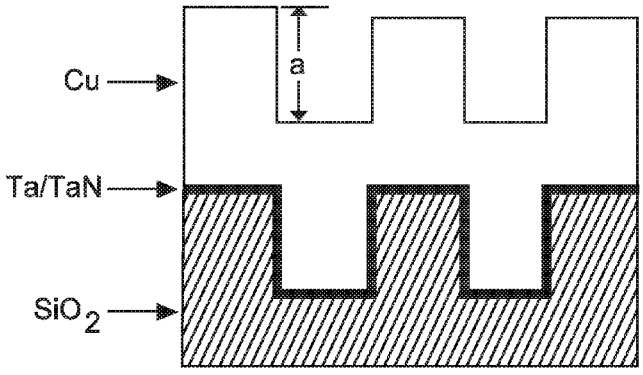


Fig. 2a

(57) Abstract: Described are a chemical-mechanical polishing (CMP) composition comprising abrasive particles in the form of organic/inorganic composite particles as well as the use of said composite particles as abrasive particles in a CMP composition and processes for the manufacture of a semiconductor device comprising chemical mechanical polishing of a substrate in the presence said CMP composition.

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